

## 24-Pin SOIC-to-22-Pin 0.400" DIP

## **FEATURES**

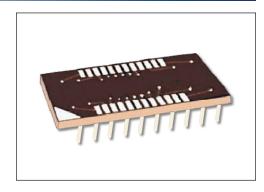
A cost-effective means of upgrading to SOIC without changing your PCB layout.

## **GENERAL SPECIFICATIONS**

- BOARD MATERIAL: 0.062 thick FR-4 with 1-oz. Cu traces, both sides
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: 200μ [5.08μ] Sn/Pb 93/7 per ASTM B579-73 over 100μ [2.54μ]
   Ni per SAE AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

## MOUNTING CONSIDERATIONS

SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71±0.08] dia.



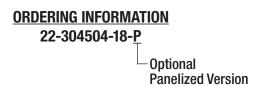
**CUSTOMIZATION:** In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

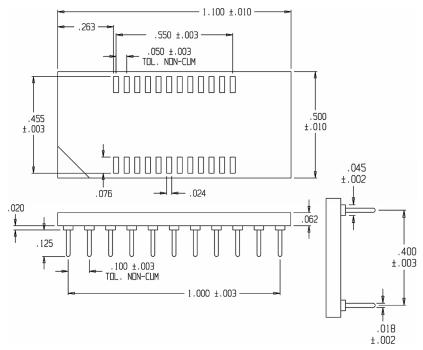
ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED

PINS 11 AND 14 NOT CONNECTED ON SOIC

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS







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